Features

- Industry-standard Architecture
- 12 ns Maximum Pin-to-pin Delay
- Zero Power – 25 µA Maximum Standby Power (Input Transition Detection)
- CMOS and TTL Compatible Inputs and Outputs
- Advanced Electrically-erasableTechnology
  - Reprogrammable
  - 100% Tested
- Latch Feature Holds Inputs to Previous Logic State
- High-reliability CMOS Process
  - 20 Year Data Retention
  - 100 Erase/Write Cycles
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Commercial and Industrial Temperature Ranges
- Dual-in-line and Surface Mount Standard Pinouts
- PCI Compliant
- Green Package Options (Pb/Halide-free/RoHS Compliant) Available

High-performance EE PLD

ATF22V10CZ
ATF22V10CQZ

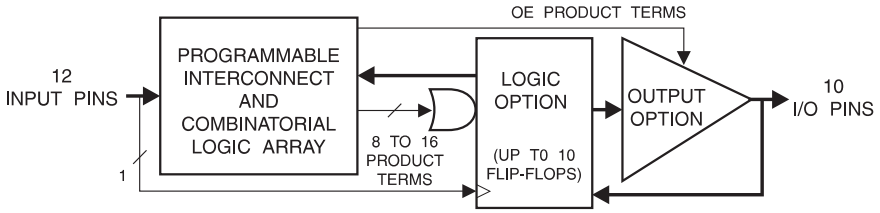
1. Desscription

The ATF22V10CZ/CQZ is a high-performance CMOS (electrically-erasable) programmable logic device (PLD) which utilizes Atmel's proven electrically-erasable Flash memory technology. Speeds down to 12 ns with zero standby power dissipation are offered. All speed ranges are specified over the full 5V ±10% range for industrial temperature ranges; 5V ±5% for commercial range 5-volt devices. The ATF22V10CZ/CQZ provides a low voltage and edge-sensing "zero" power CMOS PLD solution with "zero" standby power (5 µA typical). The ATF22V10CZ/CQZ provides a "zero" power CMOS PLD solution with 5V operating voltages, powering down automatically to the zero power-mode through Atmel's patented Input Transition Detection (ITD) circuitry when the device is idle, offering "zero" (25 µA worst case) standby power. This feature allows the user to manage total system power to meet specific application requirements and enhance reliability. Pin "keeper" circuits on input and output pins eliminate static power consumed by pull-up resistors. The "CQZ" combines the low high-frequency I_{CC} of the "Q" design with the "Z" feature.

The ATF22V10CZ/CQZ incorporates a superset of the generic architectures, which allows direct replacement of the 22V10 family and most 24-pin combinatorial PLDs. Ten outputs are each allocated 8 to 16 product terms. Three different modes of operation, configured automatically with software, allow highly complex logic functions to be realized.

0778J–PLD–11/07

Figure 1-1. Block Diagram



2. Pin Configurations

Table 2-1. Pin Configurations (All Pinouts Top View)

Pin Name	Function
CLK	Clock
IN	Logic Inputs
I/O	Bi-directional Buffers
VCC	+5V Supply

Figure 2-1. TSSOP

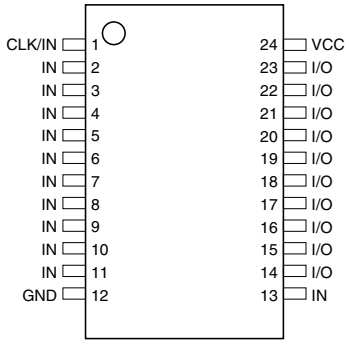


Figure 2-2. DIP/SOIC

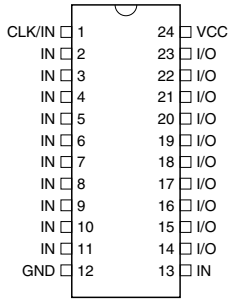
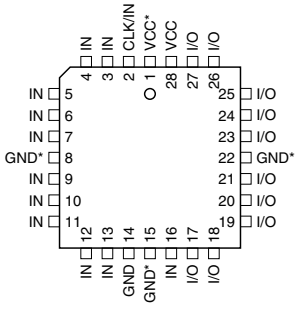


Figure 2-3. PLCC



Note: For PLCC, P1, P8, P15 and P22 can be left unconnected. For superior performance, connect VCC to pin 1 and GND to 8, 15, and 22.

3. Absolute Maximum Ratings*

Temperature Under Bias	-40°C to +85°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-2.0V to +7.0V(1)
Voltage on Input Pins with Respect to Ground During Programming	-2.0V to +14.0V(1)
Programming Voltage with Respect to Ground	-2.0V to +14.0V(1)

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V DC, which may overshoot to 7.0V for pulses of less than 20 ns.

4. DC and AC Operating Conditions

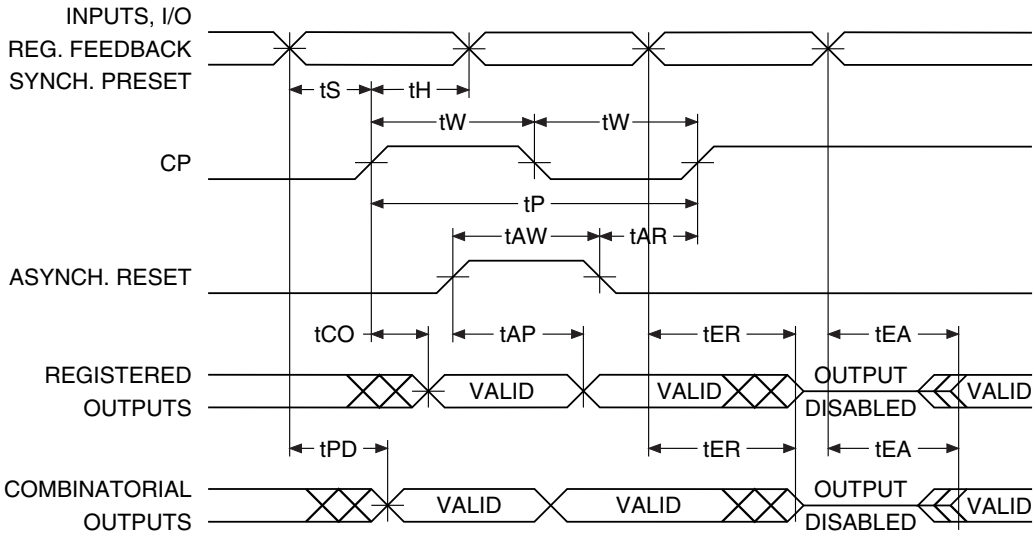
	Commercial	Industrial
Operating Temperature (Ambient)	0°C - 70°C	-40°C - 85°C
V_{CC} Power Supply	5V ± 5%	5V ± 10%

4.1 DC Characteristics

Symbol	Parameter	Condition			Min	Typ	Max	Units
I_{IL}	Input or I/O Low Leakage Current	$0 \le V_{IN} \le V_{IL}$ (Max) $3.5 \le V_{IN} \le V_{CC}$					-10	µA
I_{IH}	Input or I/O High Leakage Current						10	µA
I_{CC}	Clocked Power Supply Current	V_{CC} = Max Outputs Open, f = 15 MHz	CZ-12, 15	Com		90	150	mA
			CZ-15	Ind		90	180	mA
			CQZ-20	Com		40	60	mA
			CQZ-20	Ind		40	80	mA
I_{SB}	Power Supply Current, Standby	V_{CC} = Max V_{IN} = MAX Outputs Open	CZ-12, 15	Com		5	25	µA
			CZ-15	Ind		5	50	µA
			CQZ-20	Com		5	25	µA
			CQZ-20	Ind		5	50	µA
I_{OS}[1]	Output Short Circuit Current	V_{OUT} = 0.5V					-130	mA
V_{IL}	Input Low Voltage				-0.5		0.8	V
V_{IH}	Input High Voltage				2.0		V_{CC} + 0.75	V
V_{OL}	Output Low Voltage	$V_{IN} = V_{IH}$ or V_{IL} V_{CC} = Min, I_{OL} = 16 mA					0.5	V
V_{OH}	Output High Voltage	$V_{IN} = V_{IH}$ or V_{IL} V_{CCIO} = Min, I_{OH} = -4.0 mA			2.4			V

Note: 1. Not more than one output at a time should be shorted. Duration of short circuit test should not exceed 30 sec.

4.2 AC Waveforms



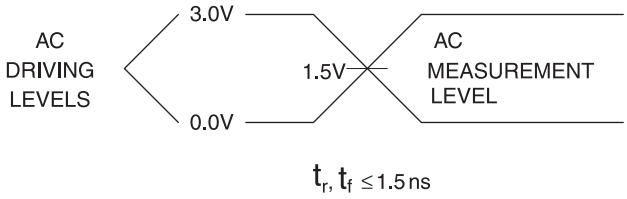
4.3 AC Characteristics[1]

Symbol	Parameter	-12		-15		-20		Units
		Min	Max	Min	Max	Min	Max	
t_{PD}	Input or Feedback to Non-registered Output	3	12	3	15	3	20	ns
t_{CF}	Clock to Feedback		6		4.5		8	ns
t_{CO}	Clock to Output	2	8	2	8	2	12	ns
t_S	Input or Feedback Setup Time	10		10		14		ns
t_H	Input Hold Time	0		0		0		ns
t_W	Clock Width	6		6		10		ns
f_{MAX}	External Feedback $1/(t_S + t_{CO})$ Internal Feedback $1/(t_S + t_{CF})$ No Feedback $1/(t_P)$		55.5 62 83.3		55.5 69 83.3	38.5 45.5 50.0		MHz MHz MHz
t_{EA}	Input to Output Enable - Product Term	3	12	3	15	3	20	ns
t_{ER}	Input to Output Disable - Product Term	2	15	3	15	3	20	ns
t_{PZX}	OE Pin to Output Enable	2	12	2	15	2	20	ns
t_{PXZ}	OE Pin to Output Disable	2	15	2	15	2	20	ns
t_{AP}	Input or I/O to Asynchronous Reset of Register	3	10	3	15	3	22	ns
t_{SP}	Setup Time, Synchronous Preset	10		10		14		ns
t_{AW}	Asynchronous Reset Width	7		8		20		ns
t_{AR}	Asynchronous Reset Recovery Time	5		6		20		ns
t_{SPR}	Synchronous Preset to Clock Recovery Time	10		10		14		ns

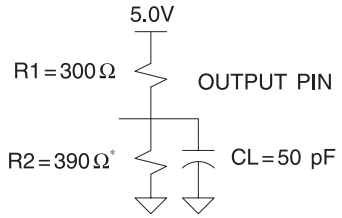
Note: 1. See ordering information for valid part numbers.

4.4 Input Test Waveforms

4.4.1 Input Test Waveforms and Measurement Levels



4.4.2 Output Test Loads



Note: Similar competitors devices are specified with slightly different loads. These load differences may affect output signals' delay and slew rate. Atmel devices are tested with sufficient margins to meet compatible device specification conditions.

4.5 Pin Capacitance

Table 4-1. Pin Capacitance (f = 1 MHz, T = 25C[1])

	Typ	Max	Units	Conditions
C_{IN}	8	10	pF	V_{IN} = 0V; f = 1.0 MHz
$C_{I/O}$	8	10	pF	V_{OUT} = 0V; f = 1.0 MHz

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

4.6 Power-up Reset

The registers in the ATF22V10CZ/CQZ are designed to reset during power-up. At a point delayed slightly from V_{CC} crossing V_{RST}, all registers will be reset to the low state. The output state will depend on the polarity of the buffer.

This feature is critical for state machine initialization. However, due to the asynchronous nature of reset and the uncertainty of how V_{CC} actually rises in the system, the following conditions are required:

1. The V_{CC} rise must be monotonic and start below 0.7V.
2. The clock must remain stable during T_{PR}.
3. After T_{PR} occurs, all input and feedback setup times must be met before driving the clock pin high.

4.7 Preload of Register Outputs

The ATF22V10CZ/CQZ's registers are provided with circuitry to allow loading of each register with either a high or a low. This feature will simplify testing since any state can be forced into the registers to control test sequencing. A JEDEC file with preload is generated when a source file

with vectors is compiled. Once downloaded, the JEDEC file preload sequence will be done automatically by most of the approved programmers after the programming.

5. Electronic Signature Word

There are 64 bits of programmable memory that are always available to the user, even if the device is secured. These bits can be used for user-specific data.

6. Security Fuse Usage

A single fuse is provided to prevent unauthorized copying of the ATF22V10CZ/CQZ fuse patterns. Once programmed, fuse verify and preload are inhibited. However, the 64-bit User Signature remains accessible. The security fuse should be programmed last, as its effect is immediate.

7. Programming/Erasing

Programming/erasing is performed using standard PLD programmers. See CMOS PLD Programming Hardware & Software Support for information on software/programming.

Figure 7-1. Programming/Erasing Timing

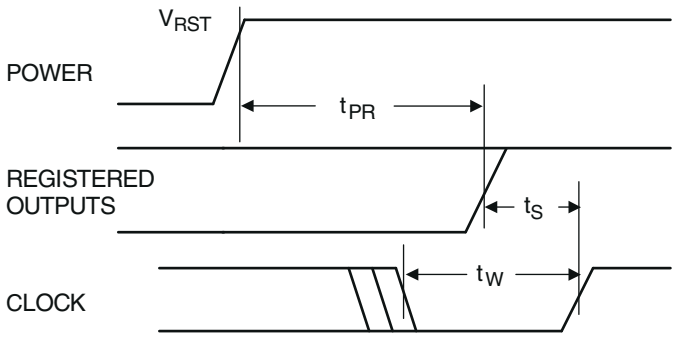


Table 7-1. Programming/Erasing

Parameter	Description	Typ	Max	Units
T_{PR}	Power-up Reset Time	600	1000	ns
V_{RST}	Power-up Reset Voltage	3.8	4.5	V

8. Input and I/O Pull-ups

All ATF22V10CZ/CQZ family members have internal input and I/O pin-keeper circuits. Therefore, whenever inputs or I/Os are not being driven externally, they will maintain their last driven state. This ensures that all logic array inputs and device outputs are at known states. These are relatively weak active circuits that can be easily overridden by TTL-compatible drivers (see input and I/O diagrams below).

Figure 8-1. Input Diagram

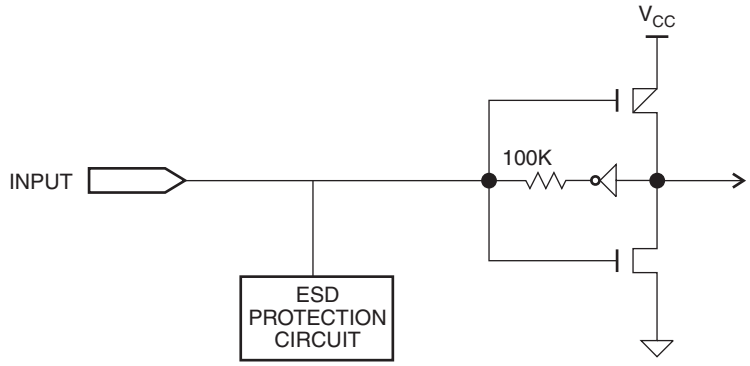
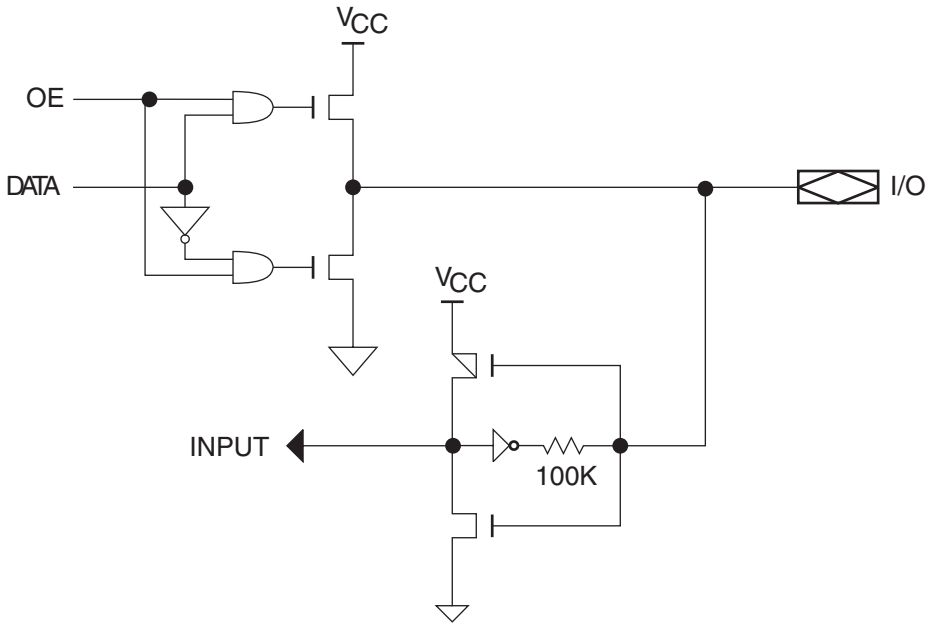


Figure 8-2. I/O Diagram



9. Compiler Mode Selection

Table 9-1. Compiler Mode Selection

	PAL Mode (5828 Fuses)	GAL Mode (5892 Fuses)
Synario	ATF22V10C (DIP) ATF22V10C (PLCC)	ATF22V10C DIP (UES) ATF22V10C PLCC (UES)
WINCUPL	P22V10 P22V10LCC	G22V10 G22V10LCC

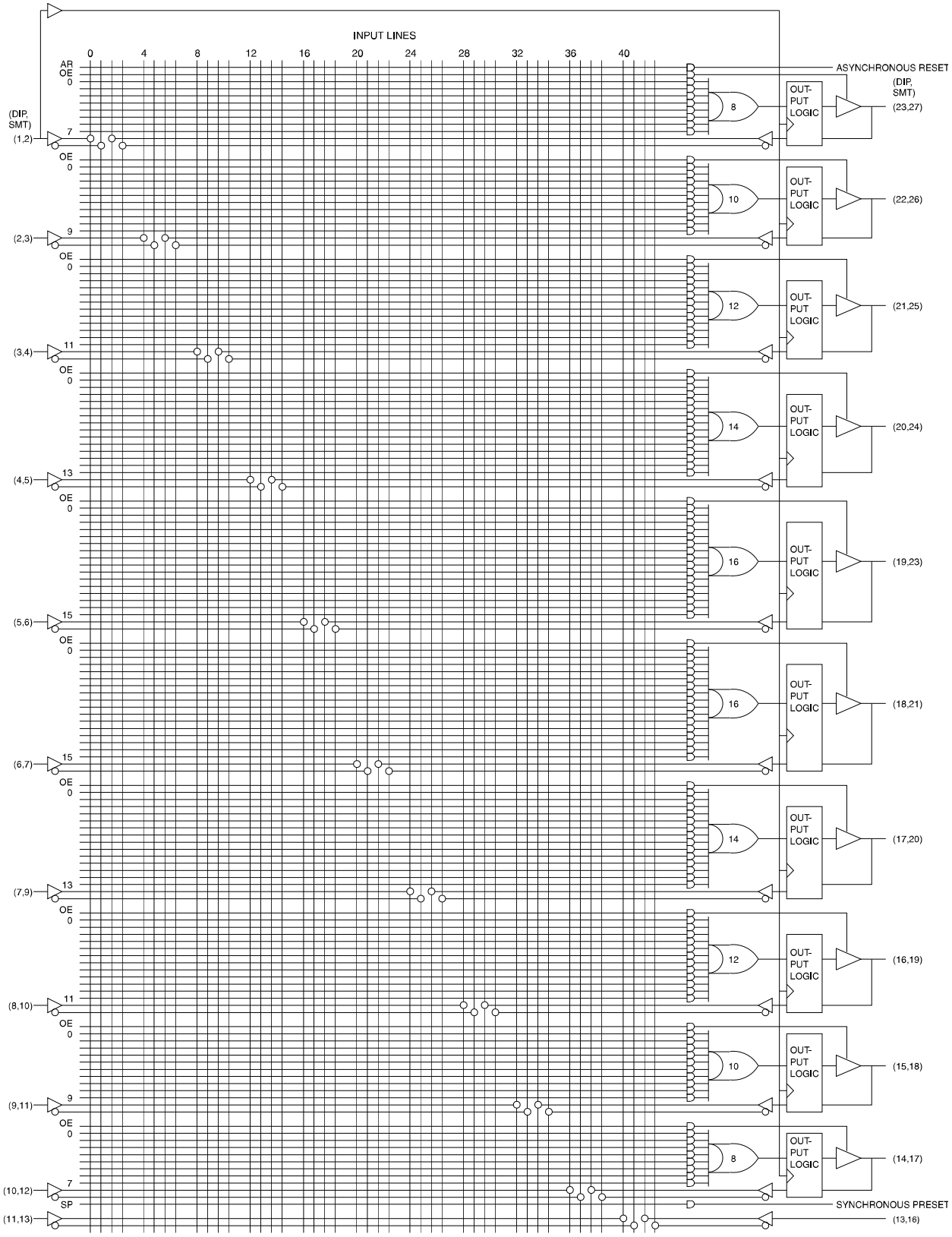
10. Functional Logic Diagram Description

The Functional Logic Diagram describes the ATF22V10CZ/CQZ architecture.

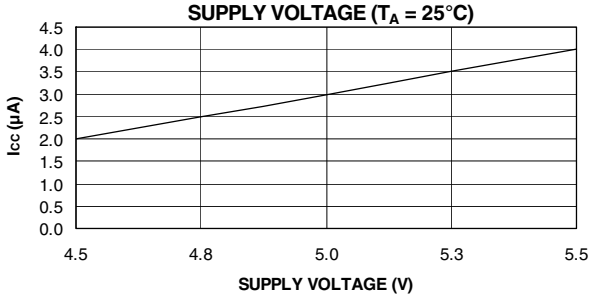
The ATF22V10CZ/CQZ has 12 inputs and 10 I/O macrocells. Each macrocell can be configured into one of four output configurations: active high/low, registered/combinatorial output.The universal architecture of the ATF22V10CZ/CQZ can be programmed to emulate most 24-pin PAL devices.

Unused product terms are automatically disabled by the compiler to decrease power consumption. A security fuse, when programmed, protects the contents of the ATF22V10CZ/CQZ. Eight bytes (64 fuses) of User Signature are accessible to the user for purposes such as storing project name, part number, revision or date. The User Signature is accessible regardless of the state of the security fuse.

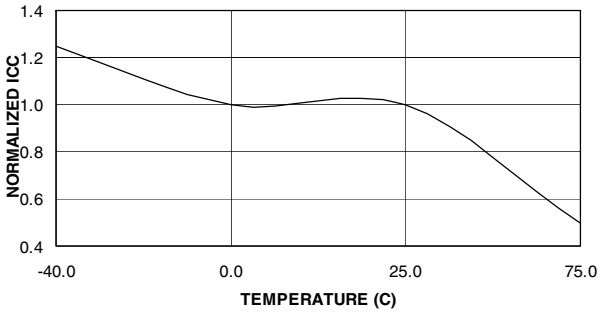
Figure 10-1. Functional Logic Diagram



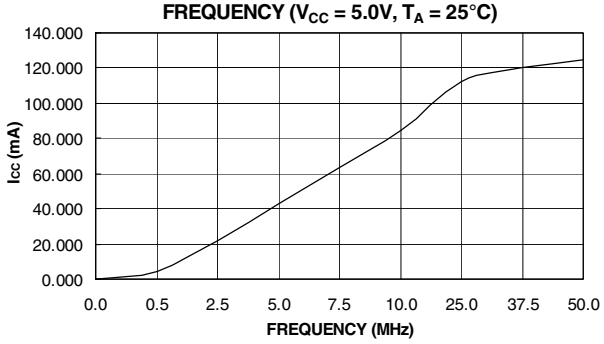
ATF22V10CZ/CQZ STAND-BY I_{CC} vs. SUPPLY VOLTAGE (T_A = 25°C)



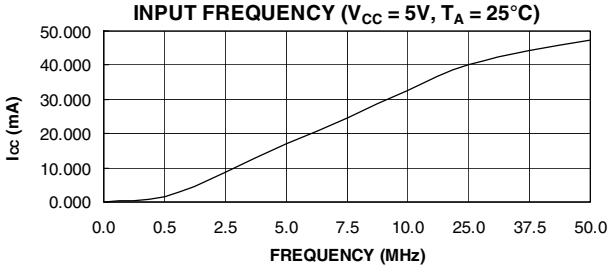
NORMALIZED ICC VS. TEMP



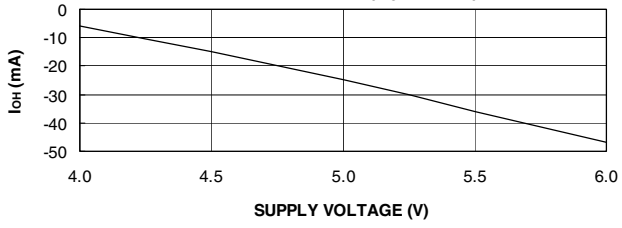
ATF22V10CZ SUPPLY CURRENT vs. INPUT FREQUENCY (V_{CC} = 5.0V, T_A = 25°C)



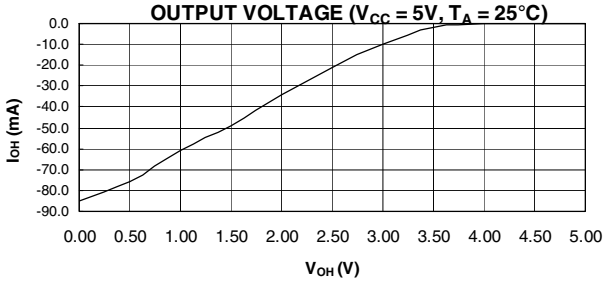
ATF22V10CQZ SUPPLY CURRENT VS. INPUT FREQUENCY (V_{CC} = 5V, T_A = 25°C)



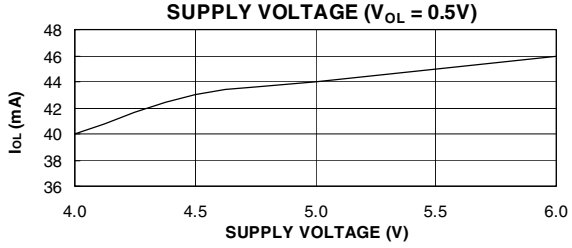
ATF22V10CZ/CQZ OUTPUT SOURCE CURRENT VS SUPPLY VOLTAGE (V_{OH} = 2.4V)



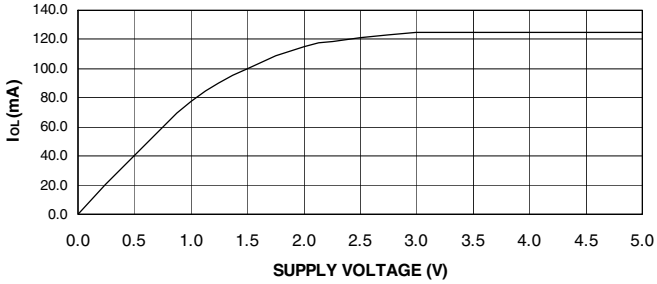
ATF22V10CZ/CQZ OUTPUT SOURCE CURRENT VS. OUTPUT VOLTAGE (V_{CC} = 5V, T_A = 25°C)



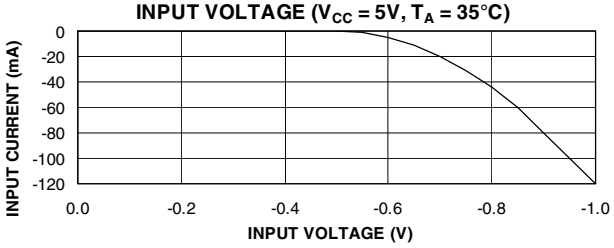
ATF22V10CZ/CQZ OUTPUT SINK CURRENT vs. SUPPLY VOLTAGE (V_{OL} = 0.5V)



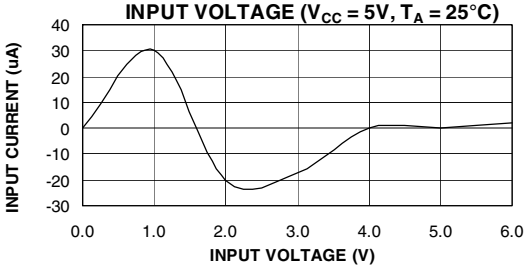
ATF22V10CZ/CQZ OUTPUT SINK CURRENT VS. SUPPLY VOLTAGE (V_{OL} = 0.5V)



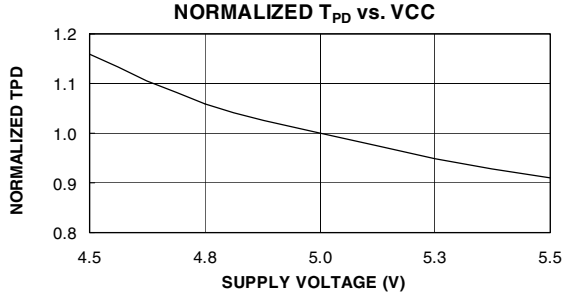
ATF22V10CZ/CQZ INPUT CLAMP CURRENT VS INPUT VOLTAGE (V_{CC} = 5V, T_A = 35°C)



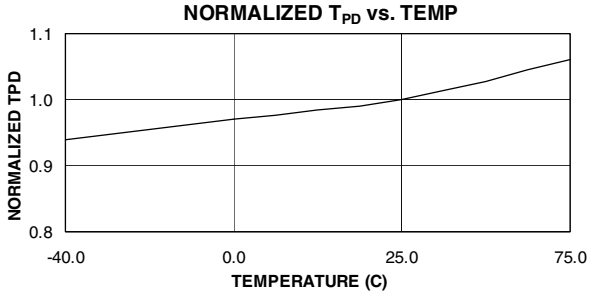
ATF22V10CZ/CQZ INPUT CURRENT VS INPUT VOLTAGE (V_{CC} = 5V, T_A = 25°C)



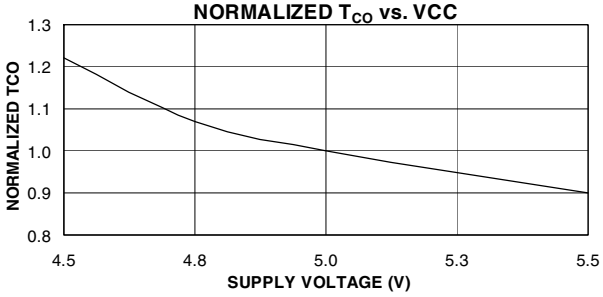
NORMALIZED T_{PD} vs. VCC



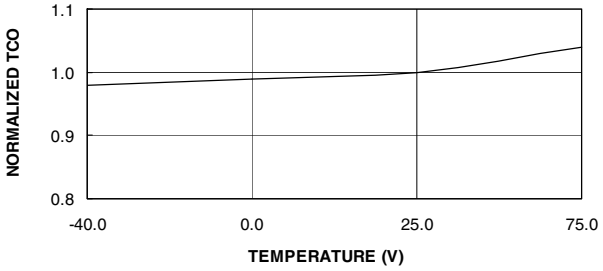
NORMALIZED T_{PD} vs. TEMP



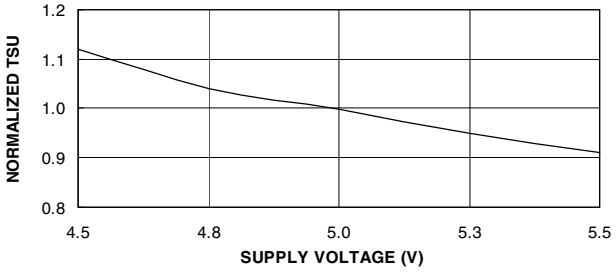
NORMALIZED T_{CO} vs. VCC



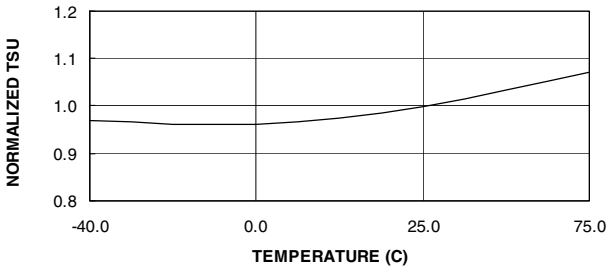
NORMALIZED T_{CO} VS TEMP



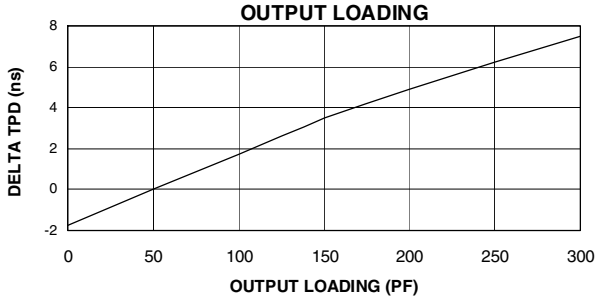
NORMALIZED T_{SU} VS VCC



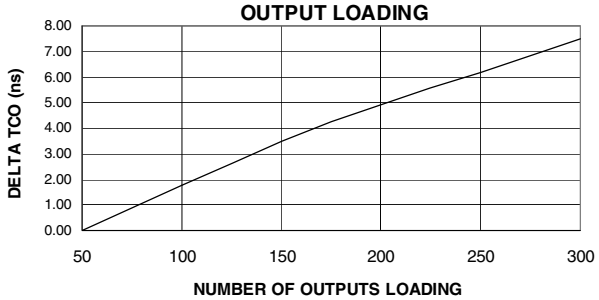
NORMALIZED T_{SU} vs. TEMP



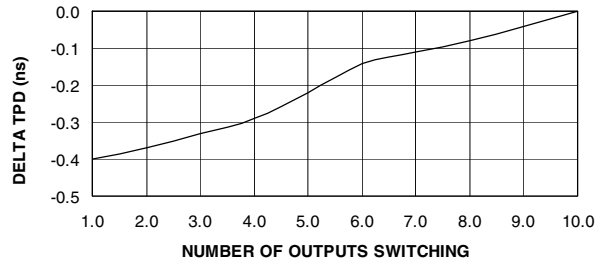
ATF22V10C DELTA T_{PD} vs. OUTPUT LOADING



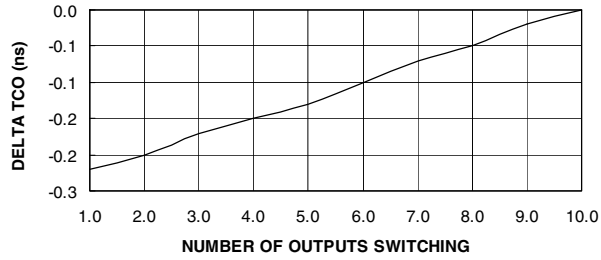
ATF22V10C DELTA T_{CO} VS. OUTPUT LOADING



DELTA T_{PD} vs. # OF OUTPUT SWITCHING



DELTA T_{CO} vs. # OF OUTPUT SWITCHING



11. Ordering Information

11.1 Standard Package Options

t_{PD} (ns)	t_S (ns)	t_{CO} (ns)	Ordering Code	Package	Operation Range
12	10	8	ATF22V10CZ-12JC ATF22V10CZ-12PC ATF22V10CZ-12SC ATF22V10CZ-12XC	28J 24P3 24S 24X	Commercial (0°C to 70°C)
15	4.5	8	ATF22V10CZ-15JC ATF22V10CZ-15PC ATF22V10CZ-15SC ATF22V10CZ-15XC	28J 24P3 24S 24X	Commercial (0°C to 70°C)
			ATF22V10CZ-15JI ATF22V10CZ-15PI ATF22V10CZ-15SI ATF22V10CZ-15XI	28J 24P3 24S 24X	Industrial (-40°C to +85°C)
20	14	12	ATF22V10CQZ-20JC ATF22V10CQZ-20PC ATF22V10CQZ-20SC ATF22V10CQZ-20XC	28J 24P3 24S 24X	Commercial (0°C to 70°C)
			ATF22V10CQZ-20JI ATF22V10CQZ-20PI ATF22V10CQZ-20SI ATF22V10CQZ-20XI	28J 24P3 24S 24X	Industrial (-40°C to +85°C)

11.2 ATF22V10CQZ Green Package Options (Pb/Halide-free/RoHS Compliant)

t_{PD} (ns)	t_S (ns)	t_{CO} (ns)	Ordering Code	Package	Operation Range
20	14	12	ATF22V10CQZ-20JU ATF22V10CQZ-20PU ATF22V10CQZ-20SU ATF22V10CQZ-20XU	28J 24P3 24S 24X	Industrial (-40°C to +85°C)

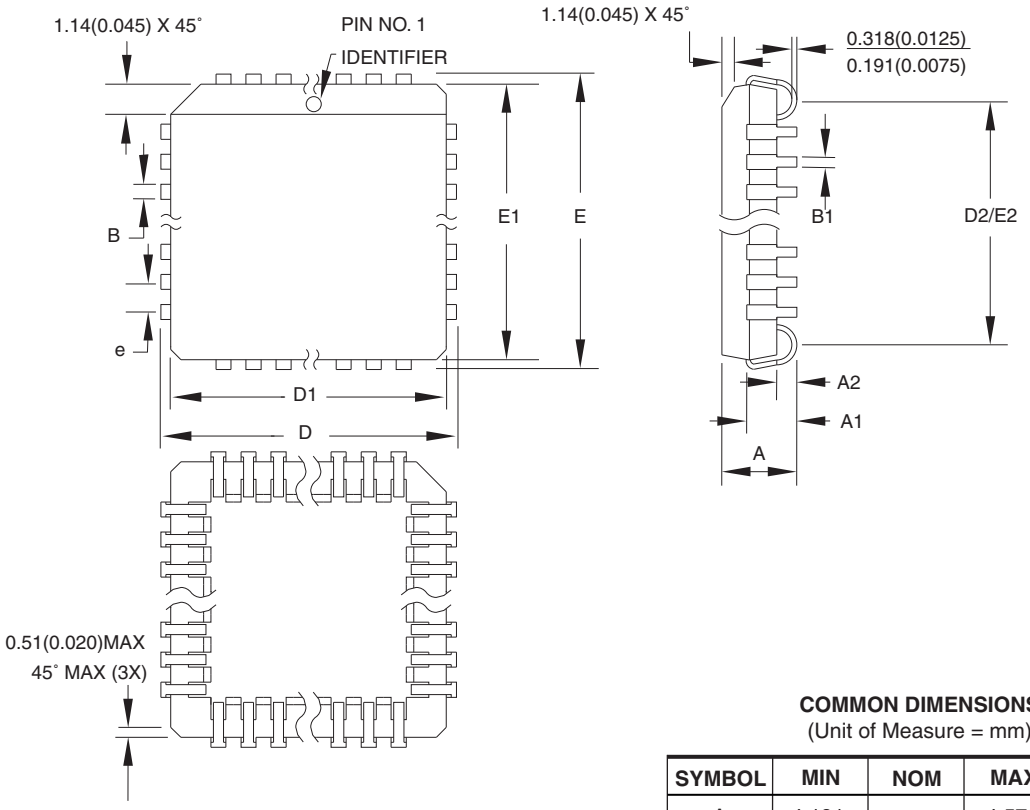
11.3 Using “C” Product for Industrial

To use commercial product for Industrial temperature ranges, down-grade one speed grade from the “I” to the “C” device (7 ns “C” = 10 ns “I”) and de-rate power by 30%.

Package Type	
28J	28-lead, Plastic J-leaded Chip Carrier (PLCC)
24P3	24-pin, 0.300", Plastic Dual Inline Package (PDIP)
24S	24-lead, 0.300" Wide, Plastic Gull-Wing Small Outline (SOIC)
24X	24-lead, 4.4 mm Wide, Plastic Thin Shrink Small Outline (TSSOP)

12. Packaging Information

12.1 28J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

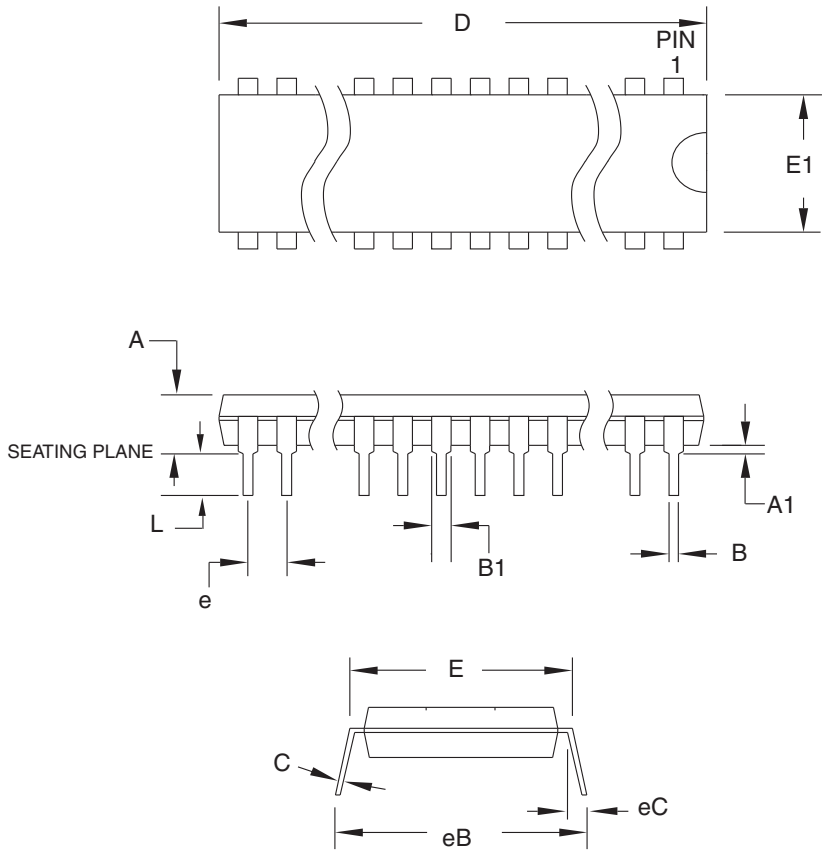
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	12.319	–	12.573	
D1	11.430	–	11.582	Note 2
E	12.319	–	12.573	
E1	11.430	–	11.582	Note 2
D2/E2	9.906	–	10.922	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**28J**, 28-lead, Plastic J-leaded Chip Carrier (PLCC)	28J	B

12.2 24P3 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

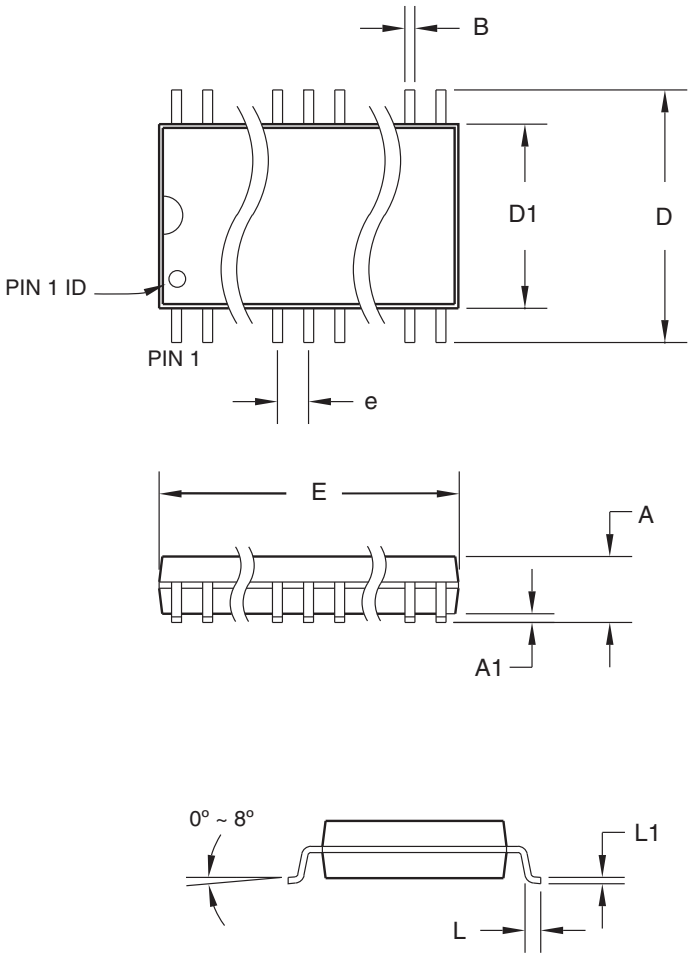
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	5.334	
A1	0.381	–	–	
D	31.623	–	32.131	Note 2
E	7.620	–	8.255	
E1	6.096	–	7.112	Note 2
B	0.356	–	0.559	
B1	1.270	–	1.651	
L	2.921	–	3.810	
C	0.203	–	0.356	
eB	–	–	10.922	
eC	0.000	–	1.524	
e	2.540 TYP			

Notes:
1. This package conforms to JEDEC reference MS-001, Variation AF.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

6/1/04

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**24P3**, 24-lead (0.300"/7.62 mm Wide) Plastic Dual Inline Package (PDIP)	24P3	D

12.3 24S – SOIC



COMMON DIMENSIONS
(Unit of Measure = mm)

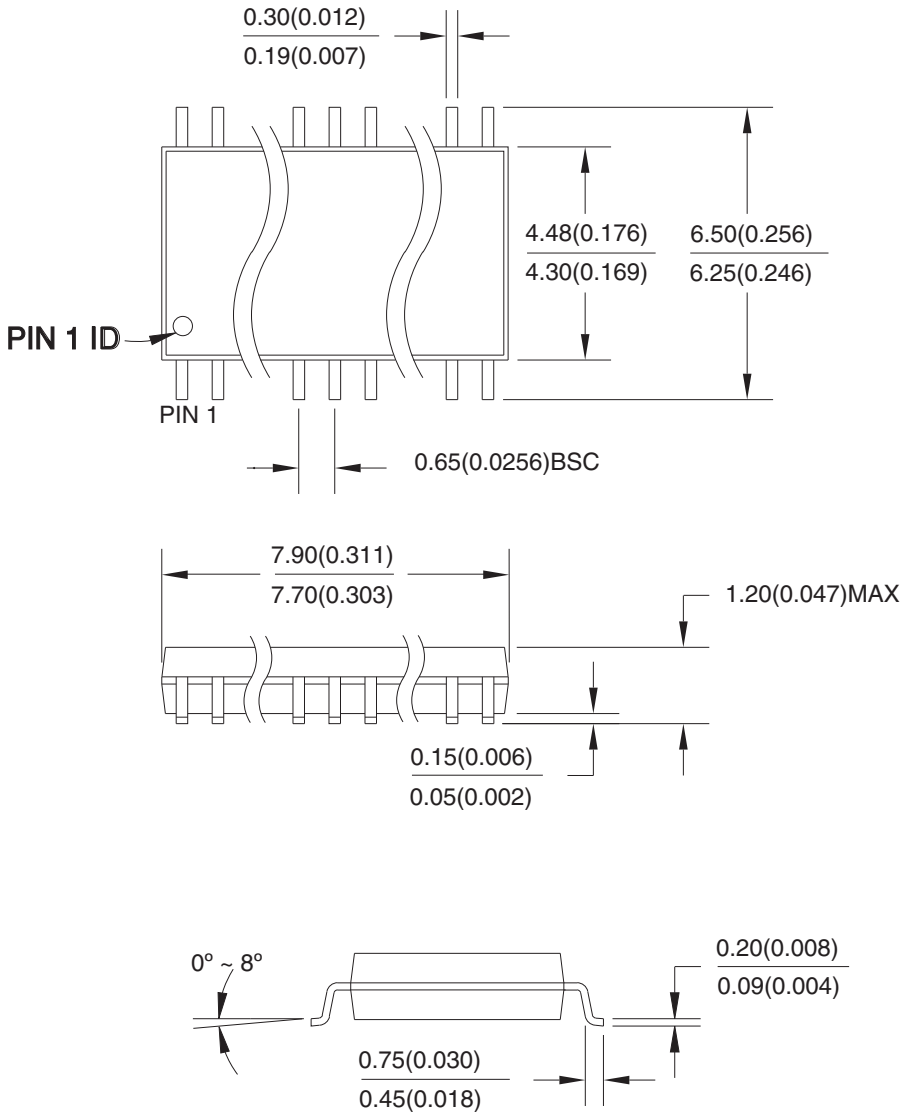
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	2.65	
A1	0.10	–	0.30	
D	10.00	–	10.65	
D1	7.40	–	7.60	
E	15.20	–	15.60	
B	0.33	–	0.51	
L	0.40	–	1.27	
L1	0.23	–	0.32	
e	1.27 BSC			

06/17/2002

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**24S**, 24-lead (0.300" body) Plastic Gull Wing Small Outline (SOIC)	24S	B

12.4 24X – TSSOP

Dimensions in Millimeter and (Inches)*
JEDEC STANDARD MO-153 AD
Controlling dimension: millimeters



04/11/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**24X**, 24-lead (4.4 mm body width) Plastic Thin Shrink Small Outline Package (TSSOP)	24X	A

13. Revision History

Version No./Release Date	History
Revision I – November 2005	1. Added Green Package options